

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|---------------------|
| L1 | 1561 | "SnAgCu" or (Sn adj Ag adj Cu) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:48 |
| L2 | 1121 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:48 |
| L3 | 486 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:50 |
| L4 | 376 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and resin and (curing or cure) and temperature | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:52 |
| L5 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and resin and (curing or cure) and temperature and (device or circuit) with inspect\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:54 |
| L6 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and resin and (curing or cure) and temperature and (device or circuit) with inspect\$4 and (baking or bake) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:54 |

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| L7 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and resin and (curing or cure) and (first near temperature) and (device or circuit) with inspect\$4 and (baking or bake) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:56 |
| L8 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and resin and (curing or cure) and (first near temperature) and (device or circuit) with inspect\$4 and (baking or bake) and (second near temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:56 |
| L9 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and resin and (curing or cure) and (first near temperature) and (device or circuit) with inspect\$4 and (baking or bake) and (second near temperature) and potting | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 07:57 |
| L10 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and (thermoset\$4 near9 resin) and (curing or cure) and (first near temperature) and (device or circuit) with inspect\$4 and (baking or bake) and (second near temperature) and potting | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 08:00 |

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| L11 | 149787 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and (thermoset\$4 near9 resin) and (curing or cure) and (first near temperature) and ((device or circuit) with inspect\$4 and (baking or bake) and (second near temperature) and potting (resin or epoxy) near9 seal\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 08:09 |
| L12 | 358 | "SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate) and seal\$4 and (thermoset\$4 near9 resin) and (curing or cure) and (first near temperature) and ((device or circuit) with inspect\$4 and (baking or bake) and (second near temperature) and potting and (resin or epoxy) near9 (seal\$4 or encapsulat\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 08:11 |
| L13 | 0 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (resin or epoxy) and (curing or cure) and (first near temperature) and ((device or circuit) with inspect\$4) and (baking or bake) and (second near temperature) and potting and (resin or epoxy) near9 (seal\$4 or encapsulat\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 08:59 |
| L14 | 117 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (resin or epoxy) and (curing or cure) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:04 |

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| L15 | 8 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (resin or epoxy) and (curing or cure) and (first near temperature) and (second near temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:05 |
| L16 | 0 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (resin or epoxy) and (curing or cure) and (first near temperature) and (second near temperature) and (baking or bake) and inspect\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:05 |
| L17 | 0 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (resin or epoxy) and (curing or cure) and (first near temperature) and (second near temperature) and (baking or bake) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:06 |
| L18 | 7 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (resin or epoxy) and (curing or cure) and (baking or bake) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:10 |
| L19 | 7 | ("SnAgCu" or (Sn adj Ag adj Cu) near9 solder with (substrate or wafer or carrier or base or plate)) and (curing or cure) and (baking or bake) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:16 |

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| L20 | 0 | (curing or cure) and (baking or bake) and (seal\$4 or encapsula\$6) with (device or circuit) and (resin or epoxy) and (first near temperature) and (second near temperature) and inspect\$4 with (circuit or device) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:18 |
| L21 | 35 | (curing or cure) and (baking or bake) and (seal\$4 or encapsula\$6) with (device or circuit) and (resin or epoxy) and (first near temperature) and (second near temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:19 |
| L22 | 5032 | (first adj temperature) and (second adj temperature) and (third adj temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:38 |
| L23 | 116 | (first adj temperature) and (second adj temperature) and (third adj temperature) and (cure or curing) with (epoxy or resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:38 |
| L24 | 67 | (first adj temperature) and (second adj temperature) and (third adj temperature) and (cure or curing) with (epoxy or resin) and (bake or baking or heat \$4) with (resin or epoxy) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:39 |
| L25 | 39 | (first adj temperature) and (second adj temperature) and (third adj temperature) and (cure or curing) with (epoxy or resin) and (bake or baking or heat \$4) with (resin or epoxy) and (circuit or device) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:39 |

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| L26 | 1 | (first adj temperature) and (second adj temperature) and (third adj temperature) and (cure or curing) with (epoxy or resin) and (bake or baking or heat \$4) with (resin or epoxy) and (inspect\$4 with (circuit or device)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:40 |
| L27 | 0 | (first adj temperature) and (second adj temperature) and (third adj temperature) and (cure or curing) with (epoxy or resin) and (bake or baking or heat \$4) with (resin or epoxy) and "SnAgCu" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:40 |
| L28 | 0 | (first adj temperature) and (second adj temperature) and (third adj temperature) and (cure or curing) with (epoxy or resin) and (bake or baking or heat \$4) with (resin or epoxy) and (Sn adj Ag adj Cu) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:41 |
| L29 | 136454 | inspect\$4 with (circuit or device) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:41 |
| L30 | 46 | inspect\$4 with (circuit or device) and ("SnAgCu" or (Sn adj Ag adj Cu)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:42 |
| L31 | 42 | inspect\$4 with (circuit or device) and ("SnAgCu" or (Sn adj Ag adj Cu)) and (substrate or wafer or carrier or base or plate) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:42 |

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| L32 | 5 | inspect\$4 with (circuit or device) and ("SnAgCu" or (Sn adj Ag adj Cu)) and (substrate or wafer or carrier or base or plate) and potting | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:43 |
| L33 | 5 | inspect\$4 with (circuit or device) and ("SnAgCu" or (Sn adj Ag adj Cu)) and (substrate or wafer or carrier or base or plate) and potting and mold\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:43 |
| L34 | 3 | ("SnAgCu" or (Sn adj Ag adj Cu)) and (third adj temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/15 09:50 |
| S1 | 15637 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2006/06/29 14:35 |
| S2 | 1967 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:21 |
| S3 | 586 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S4 | 341 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |

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| S5 | 109 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S6 | 69 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:22 |
| S7 | 53 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:23 |
| S8 | 43 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:23 |
| S9 | 41 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode and solder | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:24 |

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| S10 | 0 | resin near4 (bak\$4 or heat\$4 or anneal\$4) and cur\$4 and (temp\$4 or therm\$4) and (semiconductor or wafer or substrate) and thermoset and circuit and mold\$4 and pot\$4 and seal\$4 and lead and electrode and solder and (438/585. ccls.) | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2005/08/31 08:23 |
| S11 | 4204 | (semiconductor or substrate or wafer) and (thermoset\$4 near4 resin) and cur\$3 and bak\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/29 14:42 |
| S12 | 33 | (semiconductor or substrate or wafer) and (thermoset\$4 near4 resin) and cur\$3 and bak\$3 and seal\$3 and mold\$3 and pot\$3 and lead and temperature and chip | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/29 14:45 |
| S13 | 21 | (semiconductor or substrate or wafer) and (thermoset\$4 near4 resin) and cur\$3 and bak\$3 and seal\$3 and mold\$3 and pot\$3 and lead and temperature and (semiconductor near4 chip) and solder | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/29 14:46 |
| S14 | 38625 | (semiconductor or substrate or wafer) and (thermoset\$4 near4 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 11:52 |
| S15 | 11389 | (semiconductor or substrate or wafer) and (thermoset\$4 near4 resin) and (curing near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 11:53 |
| S16 | 107 | (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset\$4 near4 resin)) and (curing near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 11:54 |

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| S17 | 79 | (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset \$4 near4 resin)) and (curing near9 resin) and temperature | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 11:54 |
| S18 | 2 | (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset \$4 near4 resin)) and (curing near9 resin) and temperature and mold \$4 and pot\$4 and (aging near4 test\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 12:05 |
| S19 | 0 | (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset \$4 near4 resin)) and (curing near9 resin) and temperature and mold \$4 and pot\$4 and (reliab \$4 near4 test\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 12:05 |
| S20 | 0 | (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset \$4 near4 resin)) and (curing near9 resin) and temperature and mold \$4 and pot\$4 and inspect | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 12:06 |
| S21 | 6 | (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset \$4 near4 resin)) and (curing near9 resin) and temperature and mold \$4 and pot\$4 and test | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 12:16 |
| S22 | 1 | seal near9 (semiconductor or substrate or wafer) and (bak\$4 near9 (thermoset \$4 near4 resin)) and (curing near9 resin) and temperature and mold \$4 and pot\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 12:17 |
| S23 | 16 | seal near9 (semiconductor or substrate or wafer) and (bak\$4 near9 resin) and (curing near9 resin) and temperature and mold \$4 and pot\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/15 12:21 |

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| S25 | 81 | (seal or enclose) near9 (semiconductor or substrate or wafer) and (curing near9 resin) and (bak\$4 near9 resin) and temperature | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/29 08:31 |
| S26 | 14 | (seal or enclose) near9 (semiconductor or substrate or wafer) and (curing near9 resin) and (bak\$4 near9 resin) and temperature and (transfer near4 mold) and (mount\$4 near9 (semiconductor or substrate or wafer)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/11/29 10:32 |
| S27 | 17 | seal near9 (semiconductor or circuit or device) and (bak\$4 near9 resin) and (curing near9 resin) and temperature and mold \$4 and pot\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/22 09:51 |
| S28 | 273 | (resin near9 device) and ((curing or cure) near9 resin) and (bak\$4 near9 (temperature or heat)) and (semiconductor or wafer or substrate) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/22 10:02 |
| S29 | 3 | (resin near9 device) and ((curing or cure) near9 resin) and (bak\$4 near9 (temperature or heat)) and (semiconductor or wafer or substrate) and (inspect near9 device) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/22 10:23 |
| S30 | 0 | (resin near9 device) and ((curing or cure) near9 resin) and (bak\$4 near9 (temperature or heat)) and (semiconductor or wafer or substrate) and (inspect near9 device) and ((mount or holder) near9 (device or circuit)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/22 10:04 |

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| S31 | 1 | (resin near9 device) and ((curing or cure) near9 resin) and (bak\$4 near9 (temperature or heat)) and (semiconductor or wafer or substrate) and (inspect near9 device) and seal | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/22 10:24 |
| S32 | 55 | (seal\$4 near9 (resin near9 device)) and ((curing or cure) near9 resin) and (bak\$4 near9 (temperature or heat)) and (semiconductor or wafer or substrate) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 10:46 |
| S33 | 1260 | (cure or curing) near9 "thermoset resin" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 10:47 |
| S34 | 220 | (cure or curing) near9 "thermoset resin" near9 temperature | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:04 |
| S35 | 1 | (cure or curing) near9 "thermoset resin" near9 temperature and (bak\$4 near9 "thermoset resin") | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:31 |
| S36 | 4 | (cure or curing) near9 "thermoset resin" near9 temperature and (bak\$4 near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:42 |
| S37 | 80 | (cure or curing) near9 "thermoset resin" near9 temperature and (semiconductor or substrate or wafer) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:43 |
| S38 | 1 | (cure or curing) near9 "thermoset resin" near9 temperature and (semiconductor or substrate or wafer) and (bak\$4 near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:45 |

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| S39 | 1 | (cure or curing) near9 ("thermoset resin" or eopxy) near9 temperature and (semiconductor or substrate or wafer) and (bak\$4 near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:46 |
| S40 | 1 | (cure or curing) near9 ("thermoset resin" or eopxy) near9 temperature and (semiconductor or substrate or wafer) and (bak\$4 near9 (resin or epoxy)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/03 11:46 |
| S41 | 186 | seal\$4 near9 (semiconductor or substrate or wafer) and ((resin or epoxy) near9 (semiconductor or substrate or wafer)) and ((cure or curing) near9 (resin or epoxy)) and ((bake or baking) near9 (epoxy or resin)) and temperature | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/08 08:54 |
| S42 | 21 | seal\$4 near9 (semiconductor or substrate or wafer) and ((resin or epoxy) near9 (semiconductor or substrate or wafer)) and ((cure or curing) near9 (resin or epoxy)) and ((bake or baking) near9 (epoxy or resin)) and temperature and (thermal near9 (cure or curing)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/08 10:01 |
| S43 | 19669 | (transfer near4 mold) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/01/08 10:01 |
| S44 | 154768 | (chip or IC or device or semiconductor) near9 resin | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:49 |

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|-----|-------|--|---|----|----|---------------------|
| S45 | 19415 | (chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:50 |
| S46 | 377 | (chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:51 |
| S47 | 52 | (chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:51 |
| S48 | 32 | (chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) and (second near9 temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:51 |
| S49 | 0 | (chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) and (second near9 temperature) and (third near9 temperature) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:52 |
| S50 | 0 | (chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) and (second near9 temperature) and (transfer near mold\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:53 |

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|-----|------|--|---|----|----|---------------------|
| S51 | 0 | ((chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) and (second near9 temperature) and (transfer near mold\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:54 |
| S52 | 0 | ((chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) and (second near9 temperature) and (transfer near9 mold\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 07:54 |
| S53 | 9 | ((chip or IC or device or semiconductor) near9 resin and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (first near9 temperature) and (second near9 temperature) and molding and potting | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:23 |
| S54 | 2593 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:24 |
| S55 | 687 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (thermoset\$4 near resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:26 |
| S56 | 622 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (thermoset\$4 near resin) and temperature | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:27 |

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|-----|------|--|---|----|----|---------------------|
| S57 | 2 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (thermoset\$4 near resin) and temperature and (inspect near9 (device or chip or IC)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:27 |
| S58 | 2 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (thermoset\$4 near resin) and temperature and ((inspect or inspecting) near9 (device or chip or IC)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:51 |
| S59 | 2 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and (thermoset\$4 near resin) and temperature and package and inspect | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:51 |
| S60 | 3 | ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and temperature and package and inspect | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:53 |
| S61 | 7235 | package and (thermoset \$4 near resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:53 |
| S62 | 2758 | package and (thermoset \$4 near resin) and ((cure or curing) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:54 |
| S63 | 68 | package and (thermoset \$4 near resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:54 |
| S64 | 60 | package and (thermoset \$4 near resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and temperature | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:54 |

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|-----|-----|---|---|----|----|---------------------|
| S65 | 37 | package and (thermoset \$4 near resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and temperature and ((chip or IC or device or circuit) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:57 |
| S66 | 14 | package and (thermoset \$4 near resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and temperature and ((chip or IC or device or circuit) near9 resin) and inspect\$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 08:57 |
| S67 | 12 | package and (thermoset \$4 near resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and temperature and ((chip or IC or device or circuit) near9 resin) and ((inspect\$4 or monitor or test\$4) near9 (chip or IC or device or circuit)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:08 |
| S68 | 149 | ((seal\$4 or encas\$4 or enclos\$4) near9 resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and ((chip or ic or circuit or device or semiconductor) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:10 |
| S69 | 149 | ((seal\$4 or encas\$4 or enclos\$4) near9 resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and ((chip or IC or circuit or device or semiconductor) near9 resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:11 |

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|-----|--------|--|---|----|----|---------------------|
| S70 | 143 | ((seal\$4 or encas\$4 or enclos\$4) near9 resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and ((chip or IC or circuit or device or semiconductor) near9 resin) and temperature | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:11 |
| S71 | 37 | ((seal\$4 or encas\$4 or enclos\$4) near9 resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and ((chip or IC or circuit or device or semiconductor) near9 resin) and temperature and (thermoset\$4 near resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:11 |
| S72 | 11 | ((seal\$4 or encas\$4 or enclos\$4) near9 resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and ((chip or IC or circuit or device or semiconductor) near9 resin) and temperature and (thermoset\$4 near resin) and molding and potting | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:29 |
| S73 | 1 | ((seal\$4 or encas\$4 or enclos\$4) near9 resin) and ((cure or curing) near9 resin) and ((bake or baking) near9 resin) and ((chip or IC or circuit or device or semiconductor) near9 resin) and temperature and (thermoset\$4 near resin) and molding and potting and (inspect or monitor or test) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:12 |
| S74 | 399485 | ((seal\$4 or enclos\$4 or encas\$4) near9 (IC or chip or device or circuit or semiconductor)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:30 |

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|-----|-------|---|---|----|----|---------------------|
| S75 | 54589 | ((seal\$4 or enclose\$4 or encas\$4) near9 (IC or chip or device or circuit or semiconductor)) same resin | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:31 |
| S76 | 51 | ((seal\$4 or enclose\$4 or encas\$4) near9 (IC or chip or device or circuit or semiconductor)) same resin and ((curing or cure) near9 resin) and (bak\$4 near9 resin) and (thermoset\$4 near resin) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:32 |
| S77 | 34 | ((seal\$4 or enclose\$4 or encas\$4) near9 (IC or chip or device or circuit or semiconductor)) same resin and ((curing or cure) near9 resin) and (bak\$4 near9 resin) and (thermoset\$4 near resin) and ((inspect\$4 or monitor\$4 or test\$4) same (IC or chip or device or circuit or semiconductor)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/19 09:46 |
| S78 | 1899 | (bak\$4 near9 thermoset \$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:11 |
| S79 | 1070 | (bak\$4 near9 thermoset \$4) near9 resin | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:11 |
| S80 | 9 | (bak\$4 near9 thermoset \$4) near9 resin and (third near9 temperature) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:12 |
| S81 | 671 | (bak\$4 near9 thermoset \$4) near9 resin and temperature | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:26 |

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|-----|-------|--|---|----|-----|---------------------|
| S82 | 13429 | ((bak\$4 or heat\$4) near9 thermoset\$4) near9 resin and temperature | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:27 |
| S83 | 317 | ((bak\$4 or heat\$4) near9 thermoset\$4) near9 resin and (first near temperature) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:28 |
| S84 | 160 | ((bak\$4 or heat\$4) near9 thermoset\$4) near9 resin and (first near temperature) and (second near temperature) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:28 |
| S85 | 37 | ((bak\$4 or heat\$4) near9 thermoset\$4) near9 resin and (first near temperature) and (second near temperature) and (third near temperature) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:28 |
| S86 | 24 | ((bak\$4 or heat\$4) near9 thermoset\$4) near9 resin and (first near temperature) and (second near temperature) and (third near temperature) and (cure or curing or cured) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/12 14:29 |
| S87 | 2 | "6331450".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2008/03/12 14:47 |
| S88 | 20312 | (bak\$4 or cook\$4) near9 resin | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/15 10:10 |
| S89 | 25 | (bak\$4 or cook\$4) near9 resin and (third near temperature) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/15 10:10 |

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|-----|---|---|---|----|----|---------------------|
| S90 | 2 | (bak\$4 or cook\$4) near9 resin with (third near temperature) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/15 10:11 |
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